

REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
H	Add vendors CAGE 07933, 04713, and 27014. Add device type 02. Inactive case D for new design. Change input offset current limit for +25°C. Change group A subgroups for large signal voltage gain test and output voltage swing test. Editorial changes throughout.	89-07-20	M.A. Frye
J	Sheet 4: Input bias current test, I <sub>B</sub> , device type 02; for group A subgroup 1, add "-50 nA" in min column. For subgroups 2 and 3 add "-100 nA" in min column. Changes in accordance with NOR 5962-R261-94.	94-08-12	M.A. Frye
K	Update boilerplate. Changes to thermal resistance, junction-to-ambient (θ <sub>JA</sub> ). Add case outline X. Editorial changes throughout.	97-07-10	R. Monnin
L	Case outline "X" dimensions L, R, and R1 are updated. - rrp	97-12-15	R. Monnin
M	Changes to I <sub>IO</sub> , I <sub>B</sub> , V <sub>ICR</sub> , A <sub>VD</sub> , and V <sub>OL</sub> tests in table I. Add I <sub>CC</sub> and I <sub>OS</sub> tests to table I. - rrp	98-03-02	R. Monnin
N	Add device class "V" device and delete figure 1. - ro	03-04-24	R. Monnin
P	Drawing updated to reflect current requirements. - rrp	05-04-04	R. Monnin
R	Make correction to V <sub>OL</sub> test limit by deleting "20 V" and substituting "20 mV" as specified under Table I. Update boilerplate paragraphs to current MIL-PRF-38535 requirements. - ro	11-08-03	C. Saffle

THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

**CURRENT CAGE CODE 67268**

REV																				
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REV																				
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REV STATUS OF SHEETS	REV	R	R	R	R	R	R	R	R	R	R	R							
	SHEET	1	2	3	4	5	6	7	8	9	10								

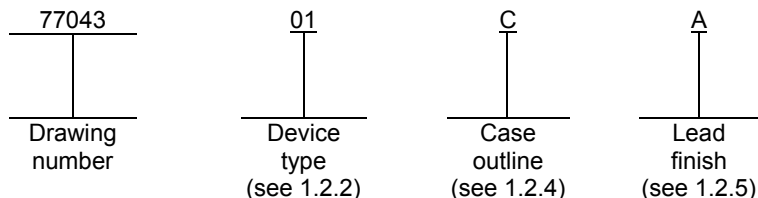
PMIC N/A	PREPARED BY WILLIAM E. SHOUP	<b>DLA LAND AND MARITIME</b> <b>COLUMBUS, OHIO 43218-3990</b> <a href="http://www.landandmaritime.dla.mil">http://www.landandmaritime.dla.mil</a>																	
<b>STANDARD MICROCIRCUIT DRAWING</b>  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A	CHECKED BY C. R. JACKSON																		
	APPROVED BY N. A. HAUCK	<b>MICROCIRCUIT, LINEAR, QUAD OPERATIONAL AMPLIFIER, MONOLITHIC SILICON</b>																	
	DRAWING APPROVAL DATE 77-09-13																		
	REVISION LEVEL R		SIZE A	CAGE CODE <b>14933</b>	<b>77043</b>														
SHEET 1 OF 10																			

1. SCOPE

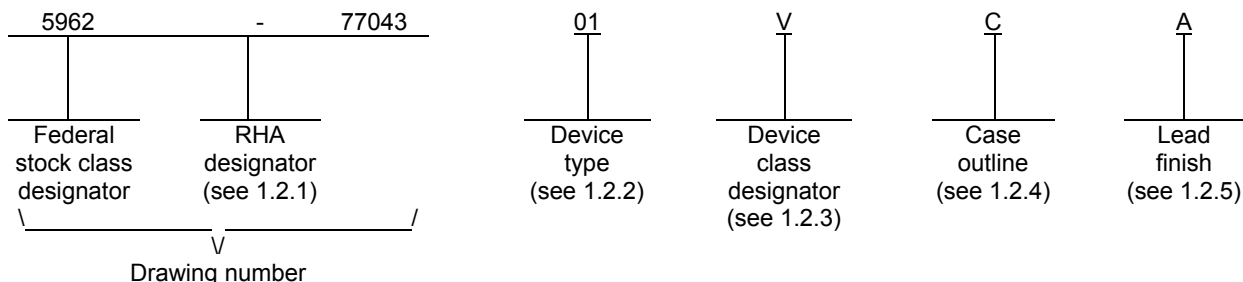
1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following examples.

For device classes M and Q:



For device class V:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	LM124	Quad operational amplifier
02	LM124A	Quad operational amplifier

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

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1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
A <u>1/</u>	GDFP5-F14 or CDFP6-F14	14	Flat pack
C	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
D	GDFP1-F14 or CDFP2-F14	14	Flat pack
X	GDFP1-G14	14	Flat pack with gull wing leads
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 2/

Supply voltage (+V) .....	32 V dc relative to ground
Differential input voltage (VID) .....	32 V dc
Input voltage (VIN) .....	-0.3 V dc to +32 V dc
Power dissipation (PD) .....	750 mW <u>3/</u>
Output short circuit to GND (one amplifier) .....	Continuous <u>4/</u>
Storage temperature range .....	-65°C to +150°C
Lead temperature (soldering, 10 seconds) .....	+300°C
Junction temperature (TJ) .....	+150°C
Thermal resistance, junction-to-case (θJC) .....	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θJA):	
Case C .....	103°C/W
Case D .....	126°C/W
Case X .....	176°C/W
Case 2 .....	91°C/W

1.4 Recommended operating conditions.

Ambient operating temperature range (TA) .....	-55°C to +125°C
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- 1/ Inactivate for new design. Acceptable only for use in equipment designed or redesigned on or before 29 November 1986.
- 2/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 3/ Dissipation is total of four amplifiers. Use external resistor to allow amplifier to saturate or reduce power dissipation in the circuit.
- 4/ Short circuits from output to +V can cause excessive heating and destruction. Maximum output current is approximately 60 mA independent of magnitude of +V. Where V supply > +15 V dc, continuous short circuits can exceed PD ratings and cause destruction. Destructive dissipation can result from simultaneous shorts on all amplifiers.

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## 2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

### DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

### DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T <sub>A</sub> ≤ +125°C +V = 5.0 V dc unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Input offset voltage	V <sub>IO</sub>	<u>1/</u>	1	01		±5	mV
			2,3			±7	
			1	02		±2	
			2,3			±4	
Input offset current	I <sub>IO</sub>	+I <sub>IN</sub> = (-I <sub>IN</sub> ), V <sub>CM</sub> = 0 V	1	01		±30	nA
			2,3			±100	
			1	02		±10	
			2,3			±30	
Input bias current	I <sub>B</sub>	+I <sub>IN</sub> or -I <sub>IN</sub> , V <sub>CM</sub> = 0 V <u>2/</u>	1	01		-150	nA
			2,3			-300	
			1	02		-50	
			2,3			-100	
Input common mode voltage range	V <sub>ICR</sub>	+V = 30 V <u>3/</u>	1	All	0	+V - 1.5	V
			2,3		0	+V - 2.0	
Large signal voltage gain	A <sub>VD</sub>	+V = 15 V (for large V <sub>O</sub> swing), R <sub>L</sub> ≥ 2 kΩ, V <sub>O</sub> = 1 V to 11 V	4	All	50		V/mV
			5,6		25		
Output voltage swing	V <sub>OUT</sub>	+V = 30 V, R <sub>L</sub> ≥ 2 kΩ	4,5,6	All	26		V
	V <sub>OH</sub>	+V = 30 V, R <sub>L</sub> ≥ 10 kΩ			27		
	V <sub>OL</sub>	R <sub>L</sub> ≥ 10 kΩ				20	mV
Common mode rejection ratio	CMRR	+V = 30 V, T <sub>A</sub> = +25°C	4	All	70		dB
Amplifier to amplifier coupling <u>3/</u>		1 kHz, 20 kHz, T <sub>A</sub> = +25°C	4	All	80		dB

See footnotes at end of table.

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TABLE I. Electrical performance characteristics – continued.

Test	Symbol	Conditions -55°C ≤ T <sub>A</sub> ≤ +125°C +V = 5.0 V dc unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Power supply rejection ratio	PSRR	T <sub>A</sub> = +25°C	4	All	65		dB
Output current source	I <sub>O</sub> (source)	+V <sub>IN</sub> = 1.0 V, -V <sub>IN</sub> = 0 V, +V = 15 V	1	All	20		mA
			2,3		10		
Output current sink	I <sub>O</sub> (sink)	+V <sub>IN</sub> = 0 V, -V <sub>IN</sub> = +1.0 V, +V = 15 V	1	All	10		mA
			2,3		5		
		+V <sub>IN</sub> = 0 V, -V <sub>IN</sub> = +1.0 V, V <sub>O</sub> = 200 mV	1		12		μA
Power supply current	I <sub>CC</sub>	+V = 30 V	1,2,3	All		1.2	mA
			1		3.0		
			2,3		4.0		
Short circuit current	I <sub>OS</sub>	V <sub>O</sub> = 0 V	1	All	-60		mA

- 1/ V<sub>O</sub> = 1.4 V dc, +V from 5 V dc to 30 V dc; and over full input common mode range ( 0 V dc to +V = -1.5 V dc ).
- 2/ The direction of the input current is out of the integrated circuit due to the PNP input state. This current is essentially constant, independent of output state, so no loading change exists on the input lines.
- 3/ If not tested, shall be guaranteed to specified limit in table I herein.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 Verification and review for device class M. For device class M, DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

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Device types	01 and 02	
Case outlines	A, C, D, X	2
Terminal number	Terminal symbol	
1	V <sub>O</sub> 1	NC
2	-V <sub>IN</sub> 1	V <sub>O</sub> 1
3	+V <sub>IN</sub> 1	-V <sub>IN</sub> 1
4	+V	+V <sub>IN</sub> 1
5	+V <sub>IN</sub> 2	NC
6	-V <sub>IN</sub> 2	+V
7	V <sub>O</sub> 2	NC
8	V <sub>O</sub> 3	+V <sub>IN</sub> 2
9	-V <sub>IN</sub> 3	-V <sub>IN</sub> 2
10	+V <sub>IN</sub> 3	V <sub>O</sub> 2
11	GND	NC
12	+V <sub>IN</sub> 4	V <sub>O</sub> 3
13	-V <sub>IN</sub> 4	-V <sub>IN</sub> 3
14	V <sub>O</sub> 4	+V <sub>IN</sub> 3
15	---	NC
16	---	GND
17	---	NC
18	---	+V <sub>IN</sub> 4
19	---	-V <sub>IN</sub> 4
20	---	V <sub>O</sub> 4

NC = No connection

FIGURE 1. Terminal connections.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>77043</b>
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4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
  - (2)  $T_A = +125^{\circ}\text{C}$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	---	---	---
Final electrical parameters (see 4.2)	1,2,3,4,5,6 <u>1/</u>	1,2,3,4,5,6 <u>1/</u>	1,2,3, <u>1/</u> 4,5,6
Group A test requirements (see 4.4)	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3,4,5,6
Group C end-point electrical parameters (see 4.4)	1	1	1
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	---	---	---

1/ PDA applies to subgroup 1.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b.  $T_A = +125^\circ\text{C}$ , minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

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4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , after exposure, to the subgroups specified in table II herein.

## 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

## 6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-0544.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

### 6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 11-08-03

Approved sources of supply for SMD 77043 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.dscclandandmaritime.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>	Reference military specification PIN
7704301AA		<u>3/</u>	M38510/11005BAX
7704301CA	01295	LM124JB	M38510/11005BCX
	27014	LM124J/883	
	<u>4/</u>	LM124DC/883B	
7704301DA	01295	LM124WB	M38510/11005BDX
7704301XA	<u>4/</u>	LM124WG/883	---
77043012A	01295	LM124FKB	---
	<u>4/</u>	LM124E/883	
7704302CA	01295	LM124AJB	---
	27014	LM124AJ/883	
7704302DA	01295	LM124AWB	---
7704302XA	27014	LM124AWG/883	---
77043022A	01295	LM124AFKB	---
	27014	LM124AE/883	
5962-7704301VCA	01295	LM124JQMLV	---

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ The "A" case outline is no longer available.
- 4/ Not available from an approved source of supply.

STANDARD MICROCIRCUIT DRAWING BULLETIN – CONTINUED.

DATE: 11-08-03

Vendor CAGE  
number

Vendor name  
and address

01295

Texas Instruments, Incorporated  
Semiconductor Group  
8505 Forest Lane  
P.O. Box 660199  
Dallas, TX 75243  
Point of contact: U.S. Highway 75 South  
P.O. Box 84, M/S 853  
Sherman, TX 75090-9493

27014

National Semiconductor  
2900 Semiconductor Drive  
P.O. Box 58090  
Santa Clara, CA 95052-8090

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